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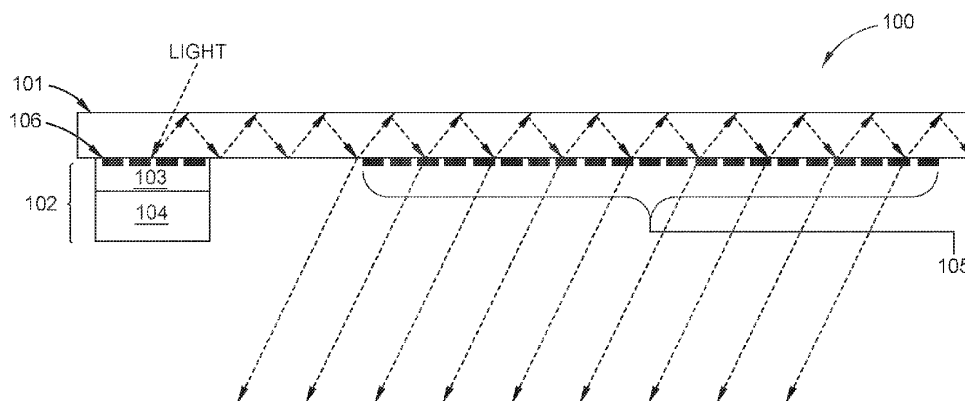


FIG. 1

(57) Abstract: The present disclosure provides a method including depositing a mirror over a waveguide, the waveguide having an input coupler and an output coupler. An encapsulation layer is deposited over the mirror. A resist is formed over the input coupler, exposing a residual encapsulation portion of the encapsulation layer over the non-input coupler area. The residual encapsulation portion of the encapsulation layer is removed, exposing a residual mirror portion of the mirror over the non-input coupler area. The residual mirror portion of the mirror of the input coupler is removed, exposing the non-input area of the waveguide. The resist over the input coupler is removed, in which the waveguide has the mirror only over the input coupler and the encapsulation layer is only over the mirror.

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WO 2024/227092 A1

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